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- TL1431 Precision Programmable Reference (2.5 V) and an Optocoupler in a Single Package
- Reference Voltage Tolerance
 - TPS5904 0.8%
 - TPS5904A 0.4%
- Controlled Optocoupler CTRs:
 - TPS5904 100% to 400%
 - TPS5904A 150% to 300%
- High Withstand Voltage (WTV), 7500 V Peak for 1 Minute
- Safety Regulatory Approvals
 - UL... File Number E65085
 - FIMKO, SEMKO, NEMKO, DEMKO
 - EN60065/IEC 65
 - EN60950/IEC 950
 - VDE 0884, Level 4 (6000-V Insulation)

description

The TPS5904 and TPS5904A optoisolated feedback amplifiers consist of the industry standard TL1431 precision programmable reference and an optocoupler. Reference-voltage tolerance for the TPS5904 is 0.8%, and for the TPS5904A, 0.4%. The devices are primarily intended for use as the error-amplifier/reference/ isolation-amplifier element in isolated ac-to-dc power supplies and dc/dc converters. The optocoupler is a gallium-arsenide (GaAs) light-emitting diode that emits at a wavelength of 940 nm, combined with a silicon phototransistor. The current transfer ratio (CTR) ranges from 100% to 400% in the standard version. The TPS5904A version with a 150%-to-300% CTR is available for higher-performance applications. When using the TPS5904 or TPS5904A, power-supply designers can reduce component count and save space in tightly packaged designs. The tight-tolerance reference eliminates the need for adjustments in many applications.

The TPS5904 and TPS5904A are characterized for operation from –40°C to 100°C. Each device is supplied in an 8-pin DIP or in an 8-pin gull-wing surface-mount package (DCS).

typical application





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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DCS OR P PACKAGE (TOP VIEW)								
LED [0	8] NC					
COMP [2	7] C					
GND [3	6] E					
FB [4	5] NC					

NC - No internal connection

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functional block diagram



Terminal Functions

TERMINAL			DECODIDITION							
NAME	NO.	1/0	DESCRIPTION							
С	7		Phototransistor collector							
COMP	2	0	Light-emitting diode and TL431 cathodes							
E	6		Phototransistor emitter							
FB	4	-	Feedback							
GND	3		Ground							
LED	1	-	Light-emitting diode anode							
NC	5, 8		No connection							

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)[†]

Input power dissipation at (or below) $T_A = 25^{\circ}C$ (see Note 1)	
Input LED current, I _{I(LED)}	50 mA
Input LED voltage, V _{I(LED)}	
Input diode reverse voltage	
Output power dissipation at (or below) $T_A = 25^{\circ}C$ (see Note 2)	
Output collector-to-emitter voltage	
Output emitter-to-collector voltage	
Output collector current	50 mA
Total continuous power dissipation at (or below) $T_A = 25^{\circ}C$ (see Note 3)	
Operating free-air temperature range, T _A	–40°C to 100°C
Storage temperature range, T _{sto}	
Total input-to-output voltage	7.5 kV peak or dc (5.3 kVrms)
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	
Flammability	(see Note 4)

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Derate linearly from 25°C at a rate of 2.95 mW/°C.

2. Derate linearly from 25°C at a rate of 1.76 mW/°C.

3. Derate linearly from 25° C at a rate of 4.12 mW/°C.

4. Optocoupler total-package flame retardancy is tested to IEC695-2-2 using a flame application time of 30 seconds. Outer mold compound is verified to meet UL 94V-0.



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electrical characteristics, $T_A = 25^{\circ}C$ (unless otherwise noted)

input

	PARAMETER	TEST CONDI	TIONS	MIN	ТҮР	MAX	UNIT	
V _F	Light-emitting diode forward vo	ltage	$V_{O(COMP)} = V_{I(FB)},$ See Figure 1	$I_{I(LED)} = 10 \text{ mA},$		1.2	1.4	v
I _R	Light-emitting diode reverse cu	rrent	V _R = 6 V				10	μΑ
V	Deference veltere	TPS5904	$V_{O(COMP)} = V_{I(FB)},$	l _{l(LED)} = 10 mA,	2.48	2.5	2.52	v
v _{ref}	Reference voltage	TPS5904A	See Figure 1	、 ,	2.49	2.5	2.51	
V _{ref(dev)}	Deviation of reference voltage temperature	over		I _{I(LED)} = 10 mA, See Figure 1		25		mV
$\frac{\Delta V_{ref}}{\Delta V_{I(LED)}}$	Ratio of reference voltage char change in input light-emitting-d	nge-to- iode voltage	$\Delta V_{I(LED)} = 4 V \text{ to } 37 V,$ See Figure 2	$I_{I(LED)} = 10 \text{ mA},$		-1.1	-2	mV/V
I _{I(FB)}	Feedback input current		I _{I(LED)} = 10 mA, See Figure 3	$R3 = 10 \ k\Omega$,		1.5	3	μΑ
I _{ref(dev)}	Deviation of reference input cu temperature	rrent over	$\begin{split} I_{I(LED)} &= 10 \text{ mA}, \\ T_A &= 25^\circ\text{C} \text{ to } 100^\circ\text{C}, \end{split}$	R3 = 10 k Ω , See Figure 3		0.5		μΑ
I _{DRV(min)}	Minimum drive current		$V_{O(COMP)} = V_{I(FB)},$	See Figure 1		0.45	1	mA
I _{I(off)}	Off-state input light-emitting-diode current		V _{I(LED)} = 37 V, See Figure 4	$V_{I(FB)} = 0,$		0.18	0.5	μΑ
Z _{ka} †	Regulator output impedance		$V_{O(COMP)} = V_{I(FB)},$ $I_{O(COMP)} = 1 \text{ mA to 50 mA}$	f ≤ 1 kHz,		0.1		Ω

[†] This symbol is not currently listed within EIA or JEDEC standards for semiconductor symbology.

output

	PARAMETER	TEST	MIN	TYP	MAX	UNIT	
I _{CEO}	Collect dark current	V _{CE} = 35 V,	See Figure 5			100	nA
V _{(BR)ECO}	Emitter-collector voltage breakdown	I _E = 100 μA		7			V

coupler

	PARAMETER	TEST CON	MIN	ТҮР	MAX	UNIT		
OTD	Current transfer ratio	TPS5904	$V_{O(COMP)} = V_{I(FB)},$	l _{l(LED)} = 5 mA,	100%		400%	
CIR		TPS5904A	$V_{CE} = 5 V,$	See Figure 6	150%		300%	
V _{CE(sat)}	Collector-emitter saturation volta	age		I _{I(LED)} = 10 mA, See Figure 6		0.1	0.2	V
V _{iso} †	Isolation voltage		$I_{IO}=10\;\mu\text{A},\qquad f=60\;\text{H}$	lz	7500			V
Cio	Input to output capacitance		$V_{IO} = 0,$ f = 1 kH	lz		0.6		pF

[†] This symbol is not currently listed within EIA or JEDEC standards for semiconductor symbology.



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PARAMETER MEASUREMENT INFORMATION



Figure 1. V_{ref} , V_F , I_{min} Test Circuit



Figure 3. I_{I(FB)} Test Circuit



Figure 2. $\Delta V_{ref} / \Delta V_{I(LED)}$ Test Circuit



Figure 4. I_{I(off)} Test Circuit



Figure 5. I_{CEO} Test Circuit



Figure 6. CTR, V_{CE(sat)} Test Circuit



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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

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TYPICAL CHARACTERISTICS



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MECHANICAL DATA

DCS (R-PDSO-G8)

PLASTIC DUAL SMALL-OUTLINE OPTO COUPLER



NOTES: A. All linear dimensions are in inches(millimeters).

B. This drawing is subject to change without notice.



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MECHANICAL DATA

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001

P (R-PDIP-T8)





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS5904	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	
TPS5904A	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	
TPS5904ADCS	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	
TPS5904DCS	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



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- C. Falls within JEDEC MS-001 variation BA.



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